




LIQUID COMPOSITION FOR SOLDER MASK

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Abstract not available for JP3188150

Abstract of corresponding document: **EP0424866**

Disclosed is a UV-curable, aqueous-developable liquid solder mask composition comprising (1) 40% to 70% of a non-reactive binder that is a film-forming random copolymer of (a) one or more (meth)acrylic alkyl ester monomers, at least one of which is an ester of a 4-12 carbon alkanol, (b) acrylic or methacrylic acid, and optionally (c) styrene or alpha -methylstyrene, (2) 20% to 40% of one or more (meth)acrylic ester monomers containing two or more ethylenic double bonds, wherein at least one of the monomers has at least four ethylenic double bonds, (3) 1% to 5% of a photoinitiator, (4) 5% to 15% of a filler, all percentages being by weight based on the nonsolvent components of the composition, and (5) 35% to 70% of an organic solvent, based on the total weight of the composition.

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